

03-16-1999

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Please record the attache

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copy thereof.

1. Name of Party(ies)
conveying an interest:Hambrecht & Quist
Guaranty Finance LLC
A California Limited
Liability CompanyAdditional name(s) of
Parties attached? No2. Name and Address of Party(ies)
receiving an interest:KULICKE & SOFFA HOLDINGS, INC.
2101 Blair Mill Road
Willow Grove, Pennsylvania 19090Additional name(s) and address(es)
of Parties attached? No

3. Description of interest conveyed:

☒ Assignment☐ Change of Name☐ Security Agreement☐ Merger

Other _____

Execution Date: January 25, 1999

4. Application number(s) or patent number(s).

Additional numbers attached? YesIf this document is being filed together with a new application,
the execution date of the application is: _____

A. Patent Application No.(s)

08/645,184
08/420,844

B. Patent No.(s)

5,422,514
5,402,0775. Name and address of party
to whom correspondence
concerning documents should
be mailed:Theodore Naccarella, Esq.
Synnestvedt & Lechner LLP
2600 Aramark Tower
Philadelphia, PA 191076. Number of applications and patents
involved: 377. Total Fee (37 C.F.R. \$3.41): \$1480.00Enclosed: ☒ (Check No. 26169)
Authorized to be Charged: ☐8. Deposit account number: 19-5425
(Attach duplicate copy of this
form if paying by deposit account.)

DO NOT USE THIS SPACE

9. I declare under penalty of perjury under the laws of the United
States of America that the foregoing is true and correct.Dated: 3.3.99
Theodore Naccarella
Registration No. 33,023Total number of pages including
cover sheet, attachments, and document: 9

PATENT

REEL: 9808 FRAME: 0068

ASSIGNMENT RECORDATION COVER SHEET**Attachment A****Provisional Patent Application Numbers**

60/097,091	60/096,972	60/097,058
60/097,169	60/097,089	60/097,108
60/097,140	60/097,069	60/097,066
60/097,164	60/097,155	60/097,103
60/097,106	60/097,167	60/097,104
60/097,101	60/097,105	60/097,067
60/097,107	60/097,102	60/097,155

Patent Application Numbers

08/764,511	09/127,579	09/127,580
09/172,178	09/191,594	

Patent Numbers

5,619,399	5,729,433	5,796,164
5,623,213	5,703,753	5,841,291
5,832,294		

ASSIGNMENT OF INTELLECTUAL PROPERTY

This ASSIGNMENT OF INTELLECTUAL PROPERTY ("Assignment") dated as of the ~~25th~~ day of January, 1999, is executed by Hambrecht & Quist Guaranty Finance, LLC, a California limited liability company ("Assignor"), in favor of Kulicke & Soffa Holdings, Inc., a Delaware corporation ("Assignee").

W I T N E S S E T H:

WHEREAS, Assignee and Assignor have entered into that certain Asset Purchase Agreement dated as of the 30th day of December, 1998 ("Asset Purchase Agreement"), pursuant to which Assignor has agreed to sell and assign to Assignee Assignor's entire right, title and interest in and to certain intellectual property listed on Attachment A hereto (the "Registered Assets"), including without limitation, any patents, patent applications, patent licenses, registered trademarks and pending trademarks. The Registered Assets were held by, and registered in the name of, MicroModule Systems, Inc. ("MMS"), which pledged the Registered Assets to Assignor as collateral for certain loans. Assignor acquired the right to dispose of the Registered Assets following the default of MMS under one or more of the loan documents and security agreements between MMS and Assignor.

WHEREAS, Assignee has agreed to purchase Assignor's right, title and interest in, to and under the Registered Assets. Capitalized terms used but not otherwise defined herein shall have the respective meanings assigned to them in the Asset Purchase Agreement.

NOW, THEREFORE, in consideration of the foregoing recitals, and the mutual promises, covenants and agreements contained in the Asset Purchase Agreement, and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Assignor does hereby sell, convey, transfer, assign and deliver to Assignee and its successors and assigns forever, all of Assignor's right, title and interest in and to the Registered Assets, to have and to hold the same unto Assignee, its successors and assigns, forever or to the full end of the term for which each Registered Asset is granted, as the case may be, as fully and entirely as the same would have been held by the Assignor had this assignment and sale not been made.

FURTHERMORE, with respect to patent applications included in the Registered Assets, Assignor, for the consideration stated above, the receipt of which is hereby acknowledged, does hereby sell, assign and transfer unto Assignee the full and exclusive right to the inventions to which the patent applications relate in the United States and the entire right, title and interest in and to any and all patents which may be granted therefor in the United States; Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said United States Patents to Assignee, and the entire right, title, and interest in and to the same, for Assignee's sole use and behoof; and for the use and behoof of Assignee's legal representatives, to the full end of the term for which said Patents may be granted, as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made.

Assignor hereby constitutes and appoints Assignee, to the extent that it may lawfully do so, with full power of substitution for Assignor, and in its name, place and stead, but on behalf and for the benefit of Assignee, to demand and enforce payment and performance of any and all obligations, claims and demands of every conceivable kind included among the Registered Assets; to demand, receive and enjoy the Registered Assets; to give receipts and releases in respect to the same; to institute, prosecute, defend and compromise any and all proceedings at law, in equity, or otherwise, which Assignee may deem desirable in order to collect, assert, enforce, defend or enjoy the benefit of any claim, demand, right, title or interest of every conceivable kind with respect to the Registered Assets; and to do any and all such acts and things in connection therewith as Assignee shall deem desirable. Assignor hereby declares that the appointment of Assignee so made, and any and all powers so granted to it, are coupled with an interest, shall be irrevocable by Assignor, and shall survive its dissolution or liquidation.

This Assignment is delivered pursuant to the Asset Purchase Agreement in order to effectuate the transfer of Assets contemplated thereunder, and is not intended to change the terms of the Asset Purchase Agreement or increase either party's rights thereunder, including, without limitation, with respect to any limits on damages. In any conflict between the terms of the Asset Purchase Agreement and this Assignment, the terms of the Asset Purchase Agreement shall prevail.

IN WITNESS WHEREOF, each of the undersigned has caused this Assignment to be duly executed on its behalf on the date first written above.

HAMBRECHT & QUIST GUARANTY FINANCE, LLC

By: Andrew W. Kahn
Andrew W. Kahn
President, Chief Operating Officer

Accepted and agreed as of the date first written above:

KULICKE & SOFFA HOLDINGS, INC.

By: _____
James Spooner
Vice President

STATE OF CALIFORNIA

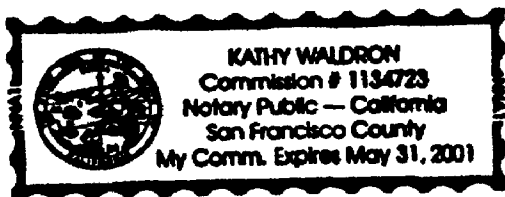
COUNTY OF San Francisco

)
) ss.:
)

On January 25, 1999 before me, Kathy Waldron personally appeared Andrew W. Kahn, personally known to me ~~(or proved to me on the basis of satisfactory evidence)~~ to be the person whose name is subscribed to the within instrument and acknowledged to me that he/~~she~~ executed the same in his/~~her~~ authorized capacity, and that by his/~~her~~ signature on such instrument the person or entity on behalf of which the person acted executed the instrument.

WITNESS my hand and official seal.

Signature Kathy Waldron (Seal)



Attachment A

Patents

1. **Packaging and Interconnect System for Integrated Circuits**
Inventor Brad Griswold, Chung Ho, William Robinette
Patent number 5422514
2. **Bare Die Carrier**
Inventor Fariborz Agahdel, Chung Ho, Brad Griswold
Patent number 5402077
3. **Mounting Assembly for Multiple Chip Module With More Than One Substrate and Computer Using Same**
Inventor Sammy Mok
Patent number 5619399
4. **Multiple Chip Module Assembly for Top of Mother Board**
Inventor Sammy Mok
Patent number 5729433
5. **Packaging and Interconnect System for Integrated Circuits**
Inventor Brad Griswold, Mark McGraw, Chung Ho, William Robinette,
 Byrong-Youl Min
Patent number 5796164
6. **Membrane Probing of Circuits**
Inventor Ken Liu, B.Y. Min, Robert Moti, Syed Husain
Patent number 5623213
7. **Mounting Assembly for Multiple Chip Module With More Than One Substrate and Computer Using Same**
Inventor Sammy Mok
Patent number 5703753
8. **Exchangeable Membrane Probe Testing of Circuits**
Inventor Ken Liu, B.Y. Min, Robert Moti, Syed Husain
Patent number 5841291
9. **Multiple Microprocessor Module**
Inventor R M Reinschmidt
Patent number 582994

Patent Applications:

1. **Programmable High Density Electronic Device Testing**
Inventor F.C. Chong
Patent Application number 08/645184
2. **An Improved Method of Planarizing Thin Film Layers Over a Printed Wiring Board Substrate**

PHTRANS\270497\2

- Inventor David J. Chazan
Patent Application number 09/127580
3. MBGA Built on Oxalic Acid Anodized Aluminum Substrate
Inventor Jim Lykins
4. A Method for Controlling Stress in Thin Film Layers Deposited Over a High Density
Interconnect Common Circuit Base
Inventor Scott M. Westbrook
Patent Application number 09/127579
5. Packaging and Interconnect System for Integrated Circuits
Inventor Brad Griswold
Patent Application number 08/420844
6. Membrane Probing of Circuit
Inventor Ken Liu
Patent Application number 08/764511
7. Rough Nickel - general technology patent
Towsend & Townsend Writing
8. Method and structure for detecting open vias in high-density interconnect substrates
Inventor David Chazen, Jim Lykins
Patent Application number 09/191594
9. Deposited thin film build-up layer dimensions as a method of relieving stress
in high-density interconnect printed
Inventor Jim Lykins, Jan Strandberg
Patent Application number 09/172178

Provisional Patent Applications

1. A Method for Filling in the Gaps Using a Squeegee
Inventor Mike Skinner
Provisional Patent number 60/097091
2. A Method and Apparatus for Filling in the Gaps by Exposing from the Back Side
Inventor Mike Skinner, Sammy Mok
Provisional Patent number 60/096972
3. A Method for Filling in the Gaps with Dummy Metal Regions
Inventor Mike Skinner, Ted Chen
Provisional Patent number 60/097058
4. "Thickness of Copper"
Inventor Jan Strandberg
Provisional Patent number 60/097169
5. A Manufacturing Process for an "extended laminate" process including modified flat panel
display tooling
Inventor David Chazan, Chung Ho, Ujwal Deshpande, Mike Skinner, Jim
Lykins
Provisional Patent number 60/097089

PHTRANS\270497\2

6. Adding Non Conductor with Plateable Seed for PTH
Inventor Jim Lykins
Provisional Patent number 60/097108
7. "Extended laminate" structure and process
Inventor Jan Stranberg
Provisional Patent number 60/097140
8. Structure and Process for Mother/daughter boards with fine line wiring
Inventor Sundar Kamath
Provisional Patent number 60/097069
9. Isolated Flip Chip or BGA to Minimize Interconnect Stress due to thermal mismatch
Inventor Sundar Kamath, David Chazan
Provisional Patent number 60/097066
10. Test and Burn in contacting structure for ubga solder ball
Inventor Sammy Mok
Provisional Patent number 60/097164
11. High Speed, high performance, fine pitch, compliance testing probe membrane structure
Inventor Fariborz Agahdel, Sammy Mok, David Chazan, Scott Westbrook
Provisional Patent number 60/097155
12. Method for testing interconnects and IC packages based upon proximity contacts
Inventor FC Chong, Sammy Mok
Provisional Patent number 60/097103
13. Membrane technology to make high-density 90 degree twist connections
Inventor Sammy Mok
Provisional Patent number 60/097106
14. Method for Parallel testing of interconnects substrate
Inventor FC Chong
Provisional Patent number 60/097167
15. A method for local compression /decompression of data for increasing testing throughput
Inventor Sammy Mok
Provisional Patent number 60/097104
16. An apparatus for the parallel test and burn-in of semiconductor chips
Inventor Fariborz Agahdel
Provisional Patent number 60/097101
17. Contact points with different shapes
Inventor Fariborz Agahdel, David Chazan, Jim Lykins
Provisional Patent number 60/097105
18. Bump First with Focused Force Structure
Inventor Fariborz Agahdel, Chung Ho, Mike Skinner
Provisional Patent number 60/097067
19. A pattern pressure compliant structure as a pressure focus mechanism

PHTRANS\270497\2

Inventor Sammy Mok, Fariborz Agahdel, Mike Skinner
Provisional Patent number 60/097107

20. Minimize Stress by Design and Adding Vias for Strength, Flatness or Thermal Management

Inventor Jim Lykins
Provisional Patent number 60/097102

21. High speed, high performance, fine pitch compliance testing probe membrane structure

Inventor Sammy Mok, Fariborz Agahdel, Scott Westbrook, David Chazen
Provisional Patent number 60/097155

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